



BAP70-04W

Silicon PIN diode

Rev. 5 — 13 December 2018

Product data sheet

1 Product profile

1.1 General description

Two planar PIN diodes in series configuration in an SOT323 small SMD plastic package.

1.2 Features and benefits

- High-voltage current control RF resistor for RF attenuators
- Low diode capacitance
- Low series inductance
- AEC-Q101 qualified

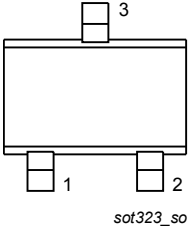
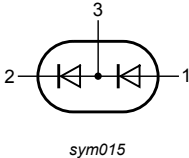
1.3 Applications

- RF attenuators and switches



2 Pinning information

Table 1. Pinning

Pin	Description	Simplified outline	Symbol
1	anode		
2	cathode		
3	common connection		

3 Ordering information

Table 2. Ordering information

Type number	Package		Version
	Name	Description	
BAP70-04W	-	plastic surface-mounted package; 3 leads	SOT323

4 Marking code

Table 3. Marking code

Type number	Marking code
BAP70-04W	1N%

5 Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	continuous reverse voltage		-	50	V
I_F	continuous forward current		-	100	mA
P_{tot}	total power dissipation	$T_{sp} \leq 90\text{ °C}$	-	260	mW
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		-65	+150	°C

6 Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-s)}$	thermal resistance from junction to solder point		230	K/W

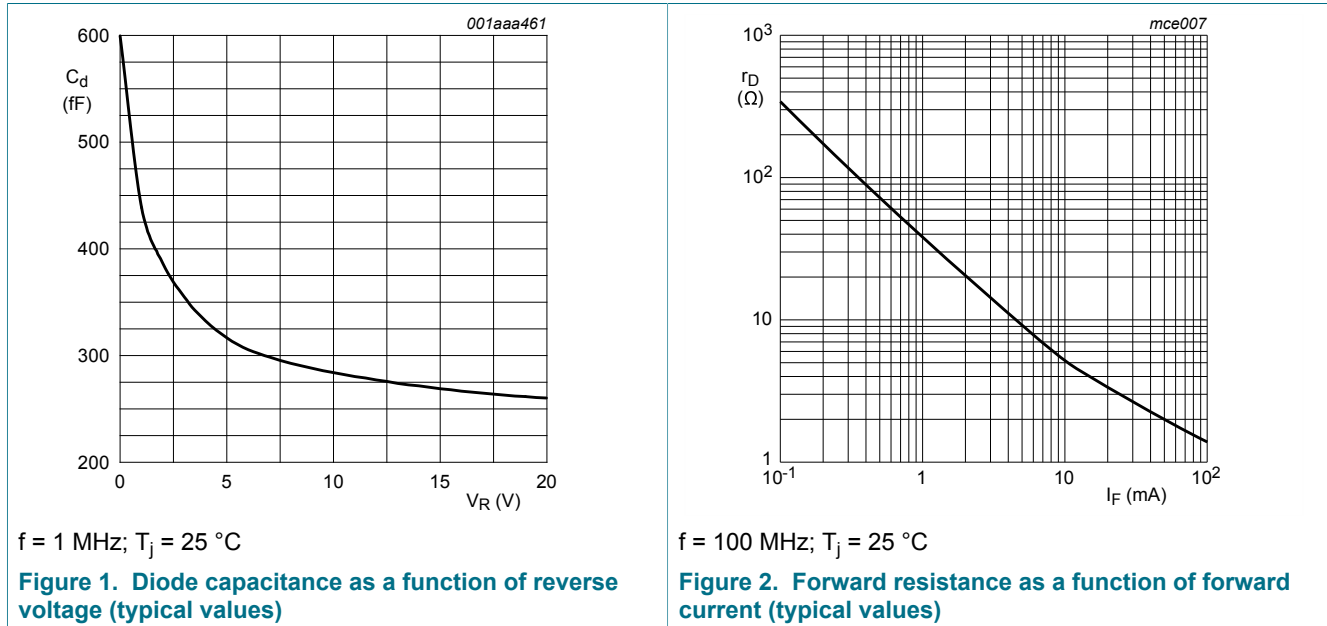
7 Characteristics

Table 6. Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage	$I_F = 50\text{ mA}$	-	0.95	1.1	V
I_R	reverse current	$V_R = 50\text{ V}$	-	-	100	nA
C_d	diode capacitance	f = 1 MHz (see Figure 1)				
		$V_R = 0\text{ V}$	-	600	-	fF
		$V_R = 1\text{ V}$	-	430	-	fF
		$V_R = 20\text{ V}$	-	250	300	fF
r_D	diode forward resistance	f = 100 MHz (see Figure 2)				
		$I_F = 0.5\text{ mA}$	-	77	100	Ω
		$I_F = 1\text{ mA}$	-	40	50	Ω
		$I_F = 10\text{ mA}$	-	5.4	7	Ω
τ_L	charge carrier life time	when switched from $I_F = 10\text{ mA}$ to $I_R = 6\text{ mA}$; $R_L = 100\ \Omega$; measured at $I_R = 3\text{ mA}$				
		-	1.25	-	μs	
L_S	series inductance	$I_F = 100\text{ mA}$; f = 100 MHz	-	1.4	-	nH

8 Graphical data



9 Package outline

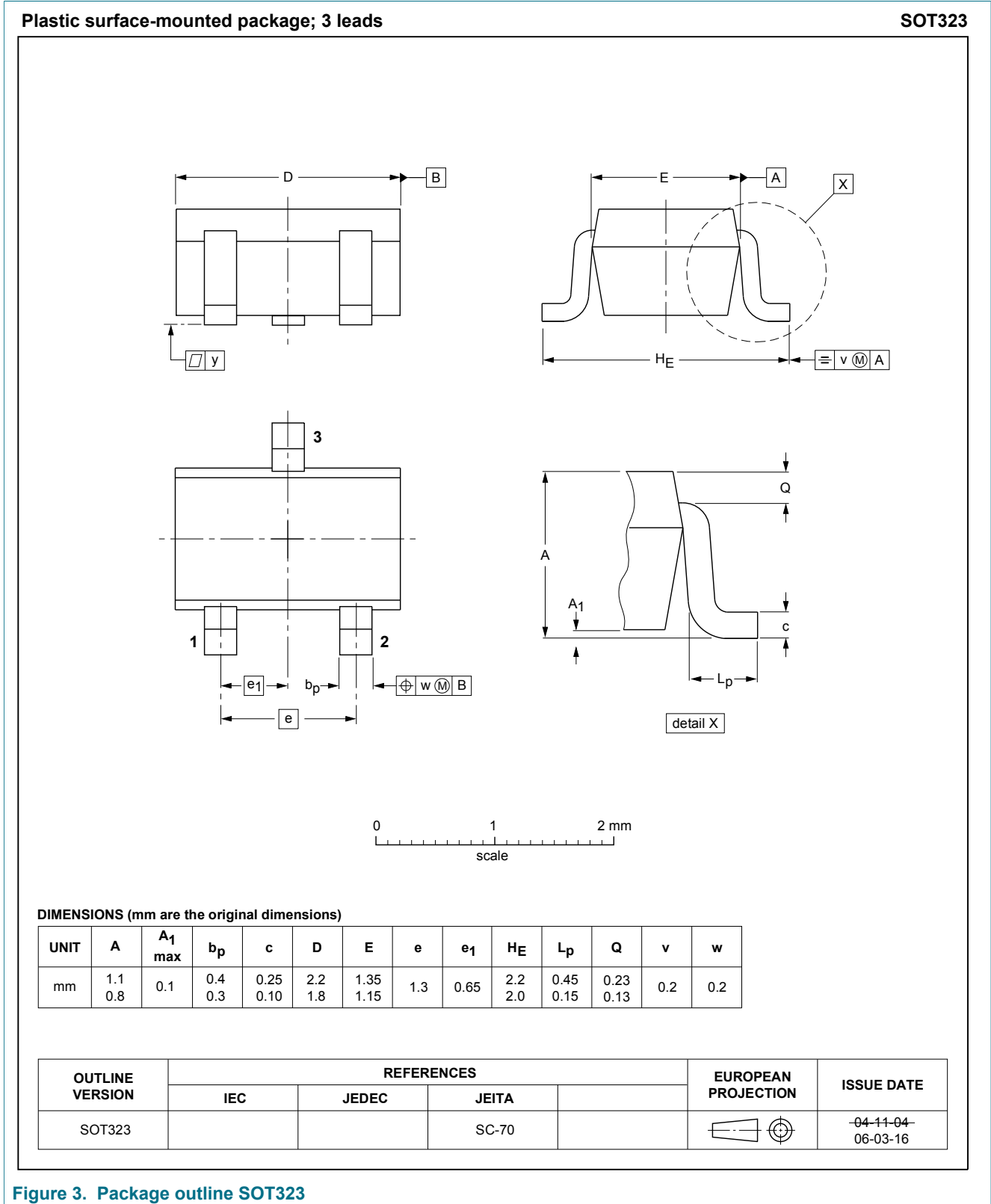


Figure 3. Package outline SOT323

10 Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAP70-04W v.5	20181213	Product data sheet	-	BAP70-04W v.4
Modifications:	<ul style="list-style-type: none">• Section 1.2 "Features and benefits" has been updated.• adapted marking code• The "Legal information" pages have been updated.			
BAP70-04W v.4	20140416	Product data sheet	-	BAP70-04W v.3
BAP70-04W v.3	20140128	Product data sheet	-	BAP70-04W v.2
BAP70-04W v.2	20070403	Product data sheet	-	BAP70-04W v.1
BAP70-04W v.1 (9397 750 12557)	20040305	Product data	-	-

11 Legal information

11.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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